

# BULK128D-B

## HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- STMicroelectronics PREFERRED SALESTYPE
- INTEGRATED ANTIPARALLEL COLLECTOR-EMITTER DIODE
- NPN TRANSISTOR
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

### **APPLICATIONS:**

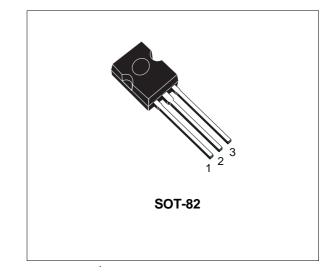
- ELECTRONIC BALLASTS FOR
  FLUORESCENT LIGHTING
- FLYBACK AND FORWARD SINGLE TRANSISTOR LOW POWER CONVERTERS

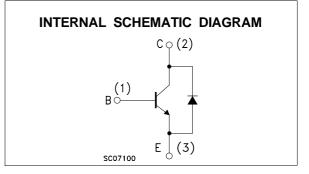
### DESCRIPTION

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability.

It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies.





#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>BE</sub> = 0)	700	V
VCEO	Collector-Emitter Voltage $(I_B = 0)$	400	V
V <sub>EBO</sub>	Emitter-Base Voltage ( $I_C = 0$ , $I_B = 2 A$ , $t_p < 10\mu s$ , $T_j < 150^{\circ}C$ )	BV <sub>EBO</sub>	V
Ιc	Collector Current	4	А
Ісм	Collector Peak Current (t <sub>p</sub> < 5 ms)	8	А
IB	Base Current	2	А
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	4	А
P <sub>tot</sub>	Total Dissipation at $T_c = 25 \ ^{\circ}C$	55	W
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

August 2001

### THERMAL DATA

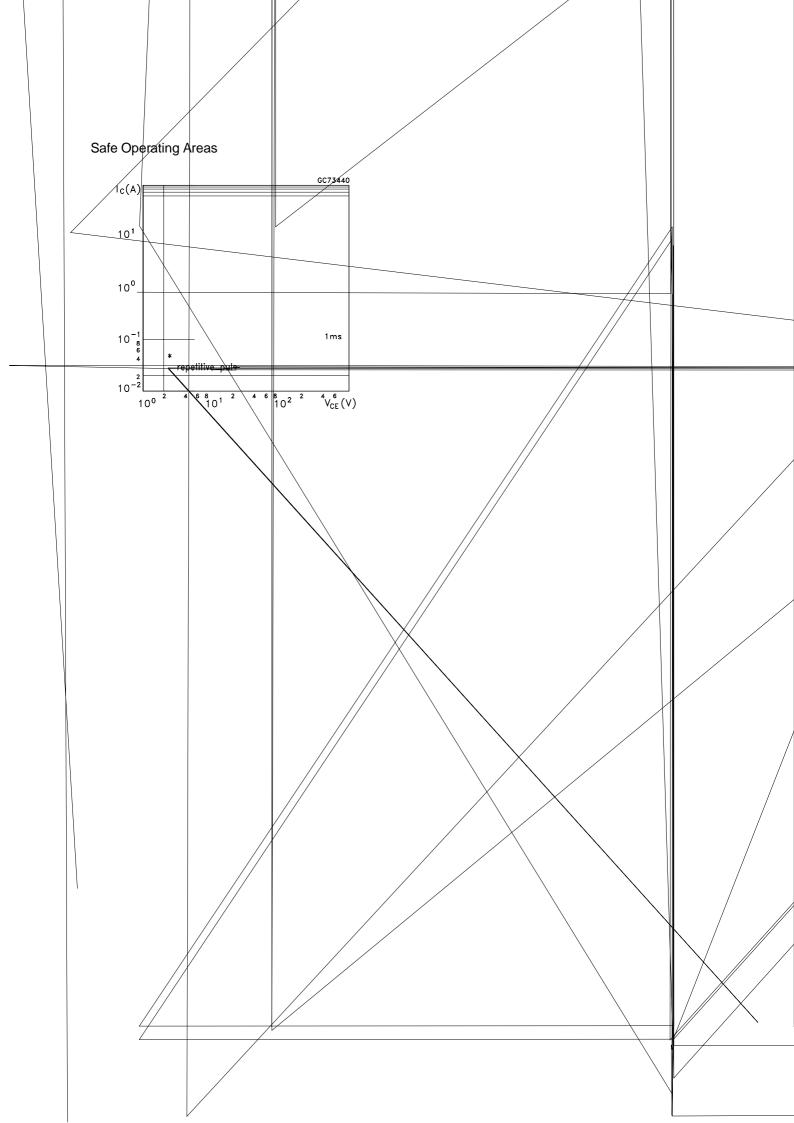
R <sub>thj-case</sub>	Thermal Resistance Junction-Case	Max	2.27	°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-Ambient	Max	80	°C/W

### **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25 \ ^{\circ}C$ unless otherwise specified)

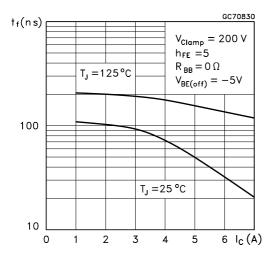
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
ICES	Collector Cut-off Current (V <sub>BE</sub> = -1.5 V)	V <sub>CE</sub> = 700 V V <sub>CE</sub> = 700 V	$T_{C} = 125 \ ^{\circ}C$			100 500	μΑ μΑ
I <sub>CEO</sub>	Collector-Emitter Leakage Current (I <sub>B</sub> = 0)	V <sub>CE</sub> = 400 V				250	μA
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage (I <sub>C</sub> = 0)	I <sub>E</sub> = 10 mA		9		18	V
V <sub>CEO(sus)</sub> *	Collector-Emitter Sustaining Voltage (I <sub>B</sub> = 0)	I <sub>C</sub> = 100 mA	L = 25 mH	400			V
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2.5 A	$I_{B} = 0.1 A$ $I_{B} = 0.2 A$ $I_{B} = 0.5 A$			0.7 1 1.5	V V V
V <sub>BE(sat)</sub> *	Base-Emitter Saturation Voltage	$I_{C} = 0.5 A$ $I_{C} = 1 A$ $I_{C} = 2.5 A$	$I_{B} = 0.1 A$ $I_{B} = 0.2 A$ $I_{B} = 0.5 A$			1.1 1.2 1.3	V V V
h <sub>FE</sub> *	DC Current Gain	$I_C = 10 \text{ mA}$ $I_C = 2 \text{ A}$	V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V	10 8		40	
Vf	Forward Voltage Drop	$I_f = 2 A$				2.5	V
ts tf	RESISTIVE LOAD Storage Time Fall Time	$V_{CC} = 250 V$ $I_{B1} = 0.4 A$ $T_p = 30 \ \mu s$	$I_{C} = 2 A$ $I_{B2} = -0.4 A$ (see fig. 2)	2	0.2	2.9	μs μs
ts tf	INDUCTIVE LOAD Storage Time Fall Time		$I_{C} = 2 A$ $V_{BE(off)} = -5 V$ $L = 200 \mu H$		0.6 0.1		μs μs

\* Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

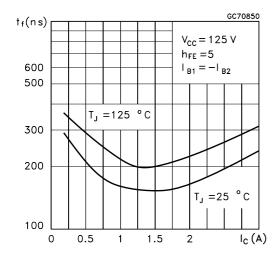
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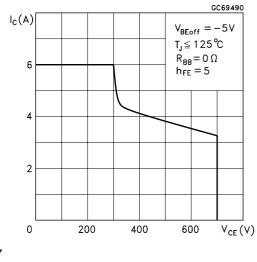
### Inductive Fall Time



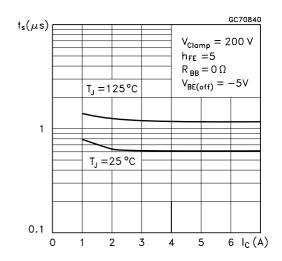
### Resistive Load Fall Time

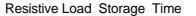


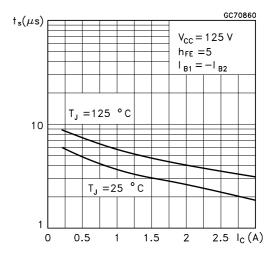
### **Reverse Biased SOA**



### Inductive Storage Time

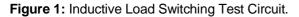






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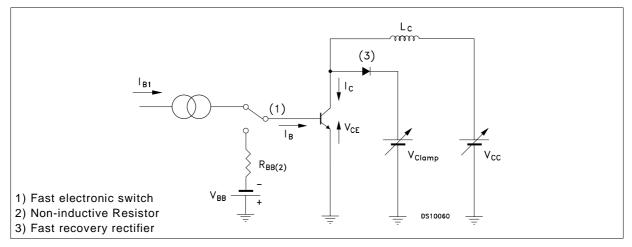
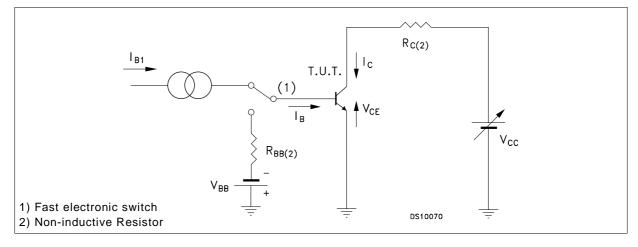


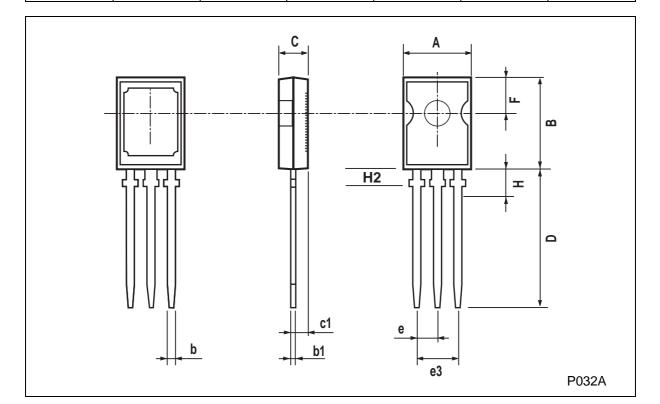
Figure 2: Resistive Load Switching Test Circuit.



### BULK128D-B

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	7.4		7.8	0.291		0.307	
В	10.5		10.8	0.413		0.444	
b	0.7		0.9	0.028		0.035	
b1	0.49		0.75	0.019		0.030	
С	2.4		2.7	0.04		0.106	
c1	1.0		1.3	0.039		0.05	
D	15.4		16	0.606		0.629	
е		2.2			0.087		
e3	4.15		4.65	0.163		0.183	
F		3.8			0.150		
Н			2.54		0.100		
H2		2.15			0.084		





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